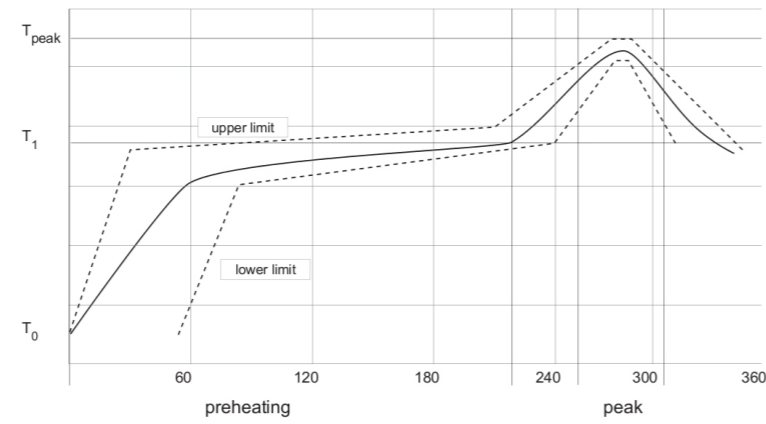


### Soldering instructions for lead-free tin soldering



#### preheating

T0 25°C (77°F)  
 T1 from 150°C (302°F) to 190°C (374°F)  
 time from 150s to 180s  
 gradient 1,5°C/s (34°F/s)

#### peak

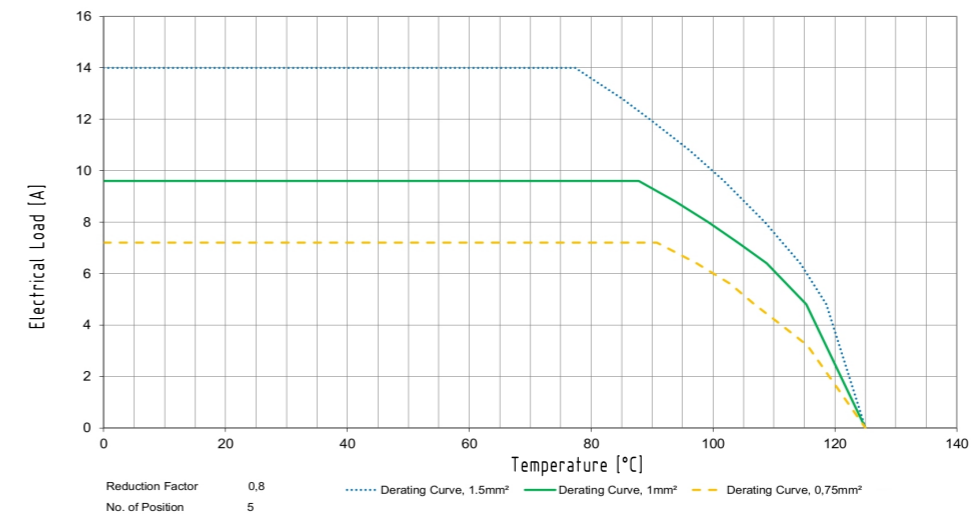
Tpeak from 260°C (500°F) to 275°C (527°F)  
 time from 10s to 30s

har-flexicon products with pure tin plated pins without lead, can be soldered by a lead-free reflow process, with a peak temperature till 275°C/527°F according to the related profile.

### Derating

The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals. The current capacity curve is valid for continuous, non interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature.

Control and test procedures according to DIN IEC 60512-5



	All rights reserved Department EL PD	All Dimensions in mm Original Size DIN A3		Scale 1:1	Free size tol.	Ref.
		Created by 408257	Inspected by LUOK	Standardisation ROEBEN	Date 2023-03-22	State Final Release
HARTING D-32339 Espelkamp		Title har-flexicon 3.50 TTPV-xx BK			Doc-Key / ECM-Nr. 100529071/UGD/001/E 50000238445	
		Type TB	Number 1402XX14101XXX		Rev. E	Page 2/2